

LM3480 100 mA, SOT-23, Quasi Low-Dropout Linear Voltage Regulator

Check for Samples: LM3480

FEATURES

- 3.3, 5, 12, and 15V Versions Available
- Packaged in the Tiny 3-Lead SOT-23 Package

APPLICATIONS

- Tiny Alternative to LM78LXX Series and Similar Devices
- Tiny 5V±5% to 3.3V, 100 mA Converter
- Post Regulator for Switching DC/DC Converter
- Bias Supply for Analog Circuits

KEY SPECIFICATIONS

- 30V Maximum Input for Operation
- 1.2V Ensured Maximum Dropout Over Full Load and Temperature Ranges
- 100 mA Ensured Minimum Load Current
- ±5% Ensured Output Voltage Tolerance Over Full Load and Temperature Ranges
- -40 to +125°C Junction Temperature Range for Operation

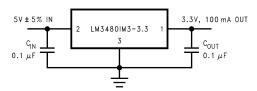
DESCRIPTION

The LM3480 is an integrated linear voltage regulator. It features operation from an input as high as 30V and a ensured maximum dropout of 1.2V at the full 100 mA load. Standard packaging for the LM3480 is the 3-lead SOT-23 package.

The 5, 12, and 15V members of the LM3480 series are intended as tiny alternatives to industry standard LM78LXX series and similar devices. The 1.2V quasi low dropout of LM3480 series devices makes them a nice fit in many applications where the 2 to 2.5V dropout of LM78LXX series devices precludes their (LM78LXX series devices) use.

The LM3480 series features a 3.3V member. The SOT-23 packaging and quasi low dropout features of the LM3480 series converge in this device to provide a very nice, very tiny 3.3V, 100 mA bias supply that regulates directly off the system 5V±5% power supply.

Typical Application Circuit



Connection Diagram

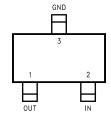


Figure 1. Top View SOT-23 Package Package Number DBZ0003A

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)

·	
Input Voltage (IN to GND)	35V
Power Dissipation (3)	333mW
Junction Temp. (3)	+150°C
Ambient Storage Temp.	−65 to +150°C
Soldering Time, Temp. ⁽⁴⁾ Wave Infrared Vapor Phase	4 sec., 260°C 10 sec., 240°C 75 sec., 219°C
ESD (5)	2kV

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is ensured. Operating Ratings do not imply ensured performance limits. For ensured performance limits and associated test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (3) The Absolute Maximum power dissipation depends on the ambient temperature and can be calculated using P = (T_J T_A)/θ_{JA} where T_J is the junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction-to-ambient thermal resistance. The 333 mW rating results from substituting the Absolute Maximum junction temperature, 150°C, for T_J, 50°C for T_A, and 300°C/W for θ_{JA}. More power can be safely dissipated at lower ambient temperatures. Less power can be safely dissipated at higher ambient temperatures. The Absolute Maximum power dissipation can be increased by 3.33 mW for each °C below 50°C ambient. It must be derated by 3.33 mW for each °C above 50°C ambient. A θ_{JA} of 300°C/W represents the worst-case condition of no heat sinking of the 3-lead plastic SOT-23 package. Heat sinking enables the safe dissipation of more power. The LM3480 actively limits its junction temperature to about 150°C.
- (4) Times shown are dwell times. Temperatures shown are dwell temperatures. For detailed information on soldering plastic small-outline packages, refer to the *Packaging Databook*.
- (5) For testing purposes, ESD was applied using the human-body model, a 100 pF capacitor discharged through a 1.5 kΩ resistor.

Operating Ratings⁽¹⁾

1 5 5	
Max. Input Voltage (IN to GND)	30V
Junction Temp. (T _J)	−40 to +125°C
Max. Power Dissipation (2)	250mW

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is ensured. Operating Ratings do not imply ensured performance limits. For ensured performance limits and associated test conditions, see the Electrical Characteristics.
- (2) As with the Absolute Maximum power dissipation, the maximum power dissipation for operation depends on the ambient temperature. The 250 mW rating appearing under Operating Ratings results from substituting the maximum junction temperature for operation, 125°C, for T_J, 50°C for T_A, and 300°C/W for θ_{JA} in P = (T_J T_A)/θ_{JA}. More power can be dissipated at lower ambient temperatures. Less power can be dissipated at higher ambient temperatures. The maximum power dissipation for operation appearing under Operating Ratings can be increased by 3.33 mW for each °C below 50°C ambient. It must be derated by 3.33 mW for each °C above 50°C ambient. A θ_{JA} of 300°C/W represents the worst-case condition of no heat sinking of the 3-lead plastic SOT-23 package. Heat sinking enables the dissipation of more power during operation.

Electrical Characteristics LM3480-3.3, LM3480-5.0

Typicals and limits appearing in normal type apply for $T_A = T_J = 25^{\circ}\text{C}$. Limits appearing in boldface type apply over the entire junction temperature range for operation, -40 to $+125^{\circ}\text{C}$. (1) (2) (3)

	Nominal Out	put Voltage (V _{NOM})	3.3\	/	5.0\	Heite	
Symbol Parameter Vout Output Voltage		Conditions	Typical	Limit	Typical	Limit	Units
V _{OUT}	Output Voltage	V _{IN} = V _{NOM} + 1.5V, 1 mA ≤ I _{OUT} ≤ 100 mA	3.30	3.17 3.14 3.43 3.46	5.00	4.80 4.75 5.20 5.25	V V(min) V(min) V(max) V(max)
ΔV _{OUT}	Line Regulation	$V_{NOM} + 1.5V \le V_{IN} \le 30V$, $I_{OUT} = 1 \text{ mA}$	10	25	12	25	mV mV(max)

- (1) A typical is the center of characterization data taken with $T_A = T_J = 25$ °C. Typicals are not ensured.
- (2) All limits are ensured. All electrical characteristics having room-temperature limits are tested during production with T_A = T_J = 25°C. All hot and cold limits are ensured by correlating the electrical characteristics to process and temperature variations and applying statistical process control.
- (3) All voltages except dropout are with respect to the voltage at the GND pin.

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Electrical Characteristics LM3480-3.3, LM3480-5.0 (continued)

Typicals and limits appearing in normal type apply for $T_A = T_J = 25^{\circ}C$. Limits appearing in boldface type apply over the entire junction temperature range for operation, -40 to $+125^{\circ}C$. (1) (2) (3)

	Nominal Outpu	ıt Voltage (V _{NOM})	3.3\	/	5.0	Unite		
Symbol	Parameter	Conditions	Typical	Limit	Typical	Limit	Units	
ΔV_{OUT}	Load Regulation	$V_{IN} = V_{NOM} + 1.5V,$ 10 mA \le I _{OUT} \le 100 mA	20	40	20	40	mV mV(max)	
I _{GND}	Ground Pin Current	V_{NOM} + 1.5V \leq V_{IN} \leq 30V, No Load	2	4	2	4	mA mA(max)	
V _{IN} - V _{OUT} Dropout Voltage		I _{OUT} = 10 mA	0.7	0.9 1.0	0.7	0.9 1.0	V V(max) V(max)	
		I _{OUT} = 100 mA	0.9	1.1 1.2	0.9	1.1 1.2	V V(max) V(max)	
e _n	Output Noise Voltage	V _{IN} = 10V, Bandwidth: 10 Hz to 100 kHz	100		150		μV_{rms}	

LM3480-12, LM3480-15

Typicals and limits appearing in normal type apply for $T_A = T_J = 25^{\circ}C$. Limits appearing in boldface type apply over the entire junction temperature range for operation, -40 to $+125^{\circ}C$. (1) (2) (3)

Nominal C	Output Voltage (V _{NOM})		12\	12V		/	11-16-
Symbol			Typical	Limit	Typical	Limit	Units
V _{OUT}	Output Voltage	$V_{IN} = V_{NOM} + 1.5V,$ 1 mA \leq I _{OUT} \leq 100 mA	12.00	11.52 11.40 12.48 12.60	15.00	14.40 14.25 15.60 15.75	V V(min) V(min) V(max) V(max)
ΔV_{OUT}	Line Regulation	$V_{NOM} + 1.5V \le V_{IN} \le 30V$, $I_{OUT} = 1 \text{ mA}$	14	40	16	40	mV mV(max)
ΔV_{OUT}	Load Regulation	$V_{IN} = V_{NOM} + 1.5V,$ 10 mA \le I _{OUT} \le 100 mA	36	60	45	75	mV mV(max)
I _{GND}	Ground Pin Current	V_{NOM} + 1.5V \leq V_{IN} \leq 30V, No Load	2	4	2	4	mA mA(max)
V _{IN} - V _{OUT}	Dropout Voltage	I _{OUT} = 10 mA	0.7	0.9 1.0	0.7	0.9 1.0	V V(max) V(max)
		I _{OUT} = 100 mA	0.9	1.1 1.2	0.9	1.1 1.2	V V(max) V(max)
e _n	Output Noise Voltage	V _{IN} = 10V, Bandwidth: 10 Hz to 100 kHz	360		450		μV_{rms}

(3) All voltages except dropout are with respect to the voltage at the GND pin.

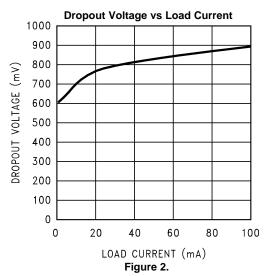
Product Folder Links: LM3480

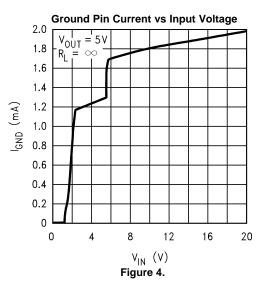
 ⁽¹⁾ A typical is the center of characterization data taken with T_A = T_J = 25°C. Typicals are not ensured.
 (2) All limits are ensured. All electrical characteristics having room-temperature limits are tested during production with T_A = T_J = 25°C. All hot and cold limits are ensured by correlating the electrical characteristics to process and temperature variations and applying statistical process control.

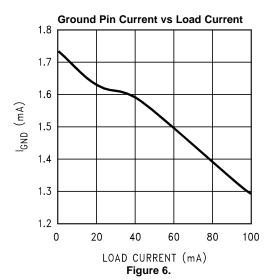


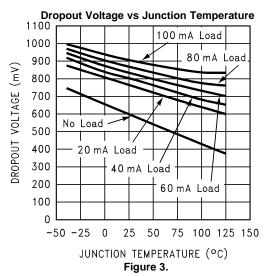
Typical Performance Characteristics

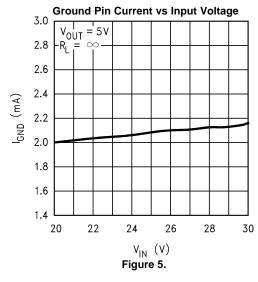
Unless indicated otherwise, $V_{IN} = V_{NOM} + 1.5V$, $C_{IN} = 0.1 \mu F$, $C_{OUT} = 0.1 \mu F$, and $T_{A} = 25$ °C.

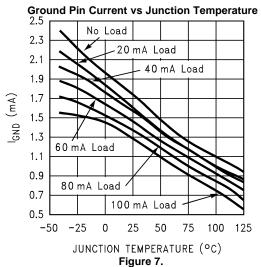








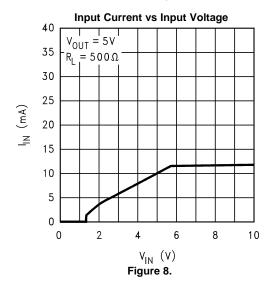


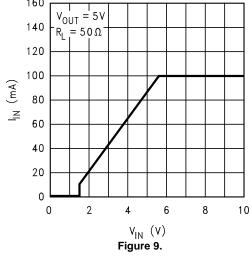




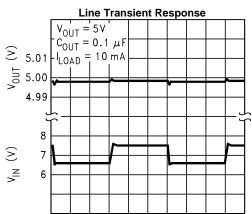
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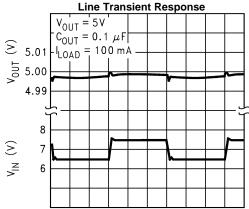
Unless indicated otherwise, $V_{IN} = V_{NOM} + 1.5V$, $C_{IN} = 0.1 \mu F$, $C_{OUT} = 0.1 \mu F$, and $T_{A} = 25$ °C.





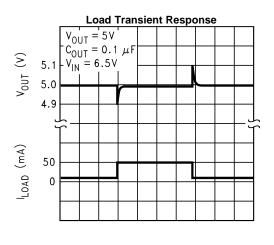
Input Current vs Input Voltage

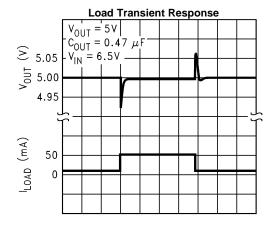










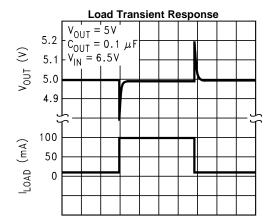


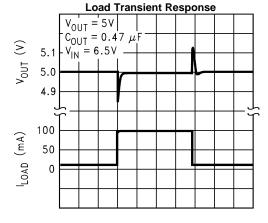
 $50 \mu s/Div$ Figure 12.

 $50 \, \mu \text{s/Div}$ Figure 13.



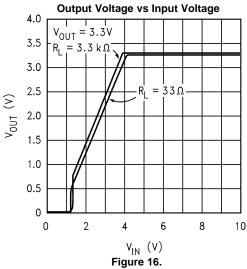
Unless indicated otherwise, $V_{IN} = V_{NOM} + 1.5V$, $C_{IN} = 0.1~\mu F$, $C_{OUT} = 0.1~\mu F$, and $T_{A} = 25^{\circ} C$.

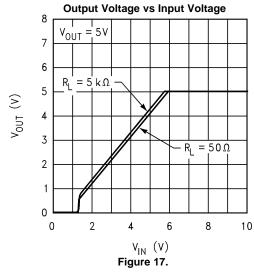


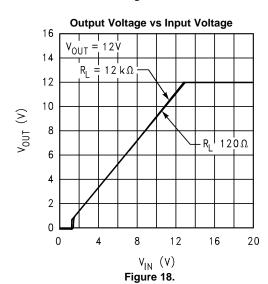


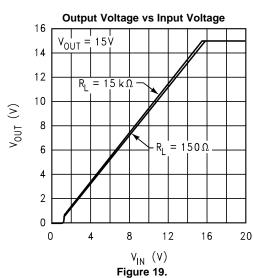








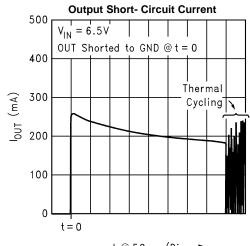




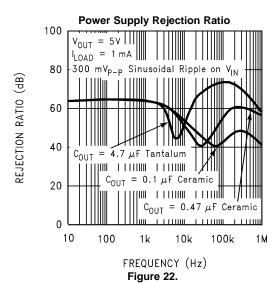
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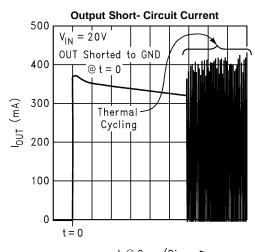


Unless indicated otherwise, $V_{IN} = V_{NOM} + 1.5V$, $C_{IN} = 0.1~\mu F$, $C_{OUT} = 0.1~\mu F$, and $T_A = 25^{\circ}C$.

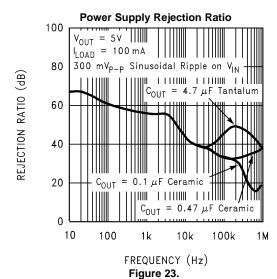


t @ 50 ms/Div → Figure 20.





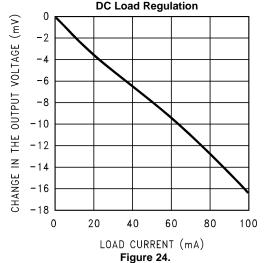
t @ 2 ms/Div → Figure 21.



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Unless indicated otherwise, $V_{IN} = V_{NOM} + 1.5V$, $C_{IN} = 0.1~\mu F$, $C_{OUT} = 0.1~\mu F$, and $T_{A} = 25^{\circ}C$. DC Load Regulation



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REVISION HISTORY

Cł	hanges from Revision D (March 2013) to Revision E	Page
•	Changed layout of National Data Sheet to TI format	7

Product Folder Links: LM3480





1-Nov-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM3480IM3-12	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	LOC	
LM3480IM3-12/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LOC	Samples
LM3480IM3-15/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LOD	Samples
LM3480IM3-3.3	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	LOA	
LM3480IM3-3.3/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LOA	Samples
LM3480IM3-5.0	NRND	SOT-23	DBZ	3	1000	TBD	Call TI	Call TI	-40 to 125	LOB	
LM3480IM3-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L0B	Samples
LM3480IM3X-12	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 125	LOC	
LM3480IM3X-12/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LOC	Samples
LM3480IM3X-15/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LOD	Samples
LM3480IM3X-3.3	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 125	LOA	
LM3480IM3X-3.3/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LOA	Samples
LM3480IM3X-5.0	NRND	SOT-23	DBZ	3	3000	TBD	Call TI	Call TI	-40 to 125	L0B	
LM3480IM3X-5.0/NOPB	ACTIVE	SOT-23	DBZ	3	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L0B	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

1-Nov-2013

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above. **Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight

- in homogeneous material)
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

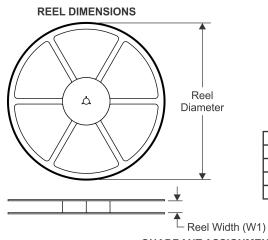
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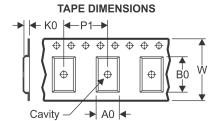
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

www.ti.com 23-Sep-2013

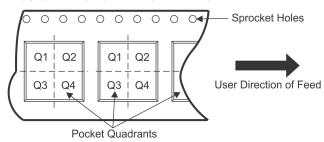
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

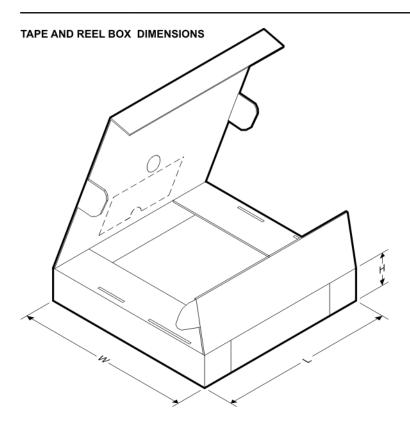
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM3480IM3-12	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3-12/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3-15/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3-3.3	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3-3.3/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3-5.0	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3-5.0/NOPB	SOT-23	DBZ	3	1000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3X-12	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3X-12/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3X-15/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3X-3.3	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3X-3.3/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3X-5.0	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM3480IM3X-5.0/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

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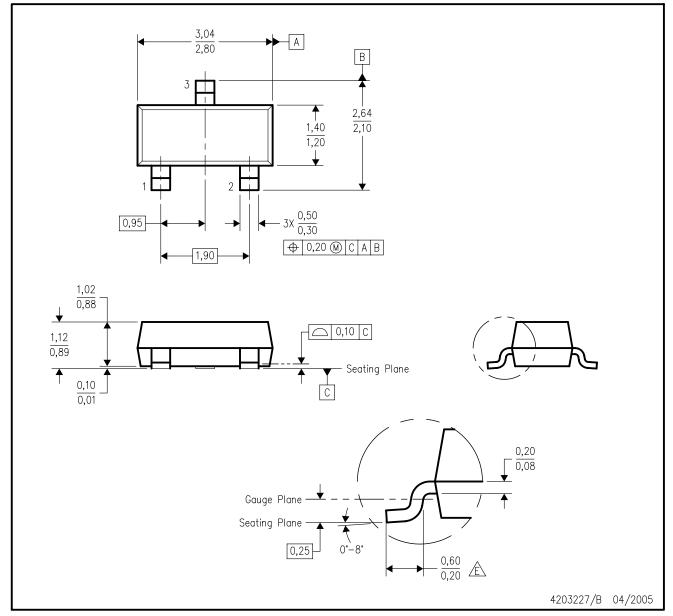


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM3480IM3-12	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM3480IM3-12/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM3480IM3-15/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM3480IM3-3.3	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM3480IM3-3.3/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM3480IM3-5.0	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM3480IM3-5.0/NOPB	SOT-23	DBZ	3	1000	210.0	185.0	35.0
LM3480IM3X-12	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM3480IM3X-12/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM3480IM3X-15/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM3480IM3X-3.3	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM3480IM3X-3.3/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM3480IM3X-5.0	SOT-23	DBZ	3	3000	210.0	185.0	35.0
LM3480IM3X-5.0/NOPB	SOT-23	DBZ	3	3000	210.0	185.0	35.0

DBZ (R-PDSO-G3)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Lead dimensions are inclusive of plating.
- D. Body dimensions are exclusive of mold flash and protrusion. Mold flash and protrusion not to exceed 0.25 per side.
- Falls within JEDEC TO-236 variation AB, except minimum foot length.



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